



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Shimizu et al.  
Serial No. : 09/536898  
Filed : March 28, 2000  
Title : HYBRID INTEGRATED CIRCUIT DEVICE

Art Unit : 2814  
Examiner : Louie, Wai Sing

Commissioner for Patents  
Washington, D.C. 20231

RESPONSE

In response to the action mailed September 24, 2002, please amend the application as follows:

In the claims:

Please amend claims 1 and 15 as follows:

1. (Twice Amended) A hybrid integrated circuit device comprising:  
a hybrid integrated circuit substrate in which at least a surface is provided with insulation;  
at least a first electrode and at least a second electrode formed on said surface and being  
disposed to cover substantially the substrate;  
a light emitting element connected with the first and second electrodes, said first and  
second electrodes configured to reflect light;  
a seal which is disposed in a periphery of said substrate; and  
a transparent substrate which is fixed to said hybrid integrated circuit substrate via  
said seal to enclose the first and second electrodes and the light emitting element within a  
sealed space formed between said hybrid integrated circuit substrate and said transparent  
substrate.

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